

Tool ID: 505
Tool Location: 122

Equipment Information Sheet

JEOL JBX-9500FS EBL System

Manager: Giovanni Sartorello 607-254-4853 Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.
Backup: John Treichler 607-254-4949
Backup: Xinwei Wu 607-254-4934

SAFETY

- No safety concerns during normal operation.
- No buddy system restrictions imposed on normal operation.

USAGE RESTRICTIONS

Please review electron beam lithography training materials in AFS (accessible on any CNF general use PC or Thin client) at
shares/public/processes_from_cnf_staff/ElectronBeamLithography/TrainingMaterials

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 30 minutes

- Put the beam current you plan to use in the "Beam Current" field in Nemo when you make the reservation.
- No more than three-hour reservation between the hours of 8 am and 8 pm, Monday through Friday.
- Maximum four reservations, or 12 hours reserved in advance at any time per person.
- The same user, group, or company must have at least three hours between any two reservations.

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Fully baked resists only; do not load samples with unbaked resist or glue or anything that may degas.

Last Updated: 03/20/2026